

WAFER DICING METHOD

ABSTRACT

A wafer dicing method comprises providing a wafer and performing a cutting procedure and a contacting procedure. The wafer includes a plurality of dies and a metal layer, wherein the metal layer is formed on a scribe line which is formed between adjacent dies. A cutter is used to cut the metal layer along the scribe line during the cutting procedure to form a plurality of dies on the wafer, and the metal layer cut by the cutter remains a plurality of metal burrs on the dies. A brush is used to contact with the metal burrs along the cutting slot during the contracting procedure to prevent each of the metal burrs from protruding from a surface of each of the dies.

FIG. 4